

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT6490635

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
ZVI OR-BACH	01/11/2021
DEEPAK SEKAR	01/10/2021
MONOLITHIC 3D INC.	01/10/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MONOLITHIC 3D INC.
<b>Street Address:</b>	1662 COVE POINT RD
<b>City:</b>	KLAMATH FALLS
<b>State/Country:</b>	OREGON
<b>Postal Code:</b>	97601
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17145678
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	4088399533
<b>Email:</b>	Brian@Monolithic3D.com
<b>Correspondent Name:</b>	BRIAN CRONQUIST
<b>Address Line 1:</b>	1662 COVE POINT RD
<b>Address Line 4:</b>	KLAMATH FALLS, OREGON 97601
<b>ATTORNEY DOCKET NUMBER:</b>	MONOLITHIC3D-15HBVN_11
<b>NAME OF SUBMITTER:</b>	BRIAN CRONQUIST
<b>SIGNATURE:</b>	/Brian Cronquist/
<b>DATE SIGNED:</b>	01/11/2021
<b>Total Attachments: 3</b>	
source=Monolithic3D-15HBVN_11_Assignment_Zvi signed#page1.tif	
source=Monolithic3D-15HBVN_11_Assignment_Deepakbcs & Brians#page1.tif	
source=Monolithic3D-15HBVN_11_Assignment_Deepakbcs & Brians#page2.tif	

**ASSIGNMENT**

Whereas, I, **Zvi Or-Bach (hereinafter referred to as Assignor(s))**, residing in **Haifa, Israel**; have made a certain invention, and executed United States Patent Application entitled:

**A 3D SEMICONDUCTOR DEVICE AND STRUCTURE WITH MEMORY**

as described in U.S. Patent Application Serial No. 17/tbd and filed on about January 11, 2021;  
and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601-9300 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

**INVENTOR:**

**DATE** on 1.11.2021

(**Zvi**

First Name

*Zvi Or-Bach*

Middle Initial

**Or-Bach)**

Last Name

ASSIGNMENT

Whereas, I, **Deepak Sekar** (hereinafter referred to as Assignor(s)), residing in **Sunnyvale, California**; have made a certain invention, and executed United States Patent Application entitled:

**A 3D SEMICONDUCTOR DEVICE AND STRUCTURE WITH MEMORY**

as described in U.S. Patent Application Serial No. 17/tbd and filed on about January 11, 2021; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601-9300 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

**INVENTOR:**

DATE on

10 Jan 2021



(Deepak

Sekar)

First Name

Middle Initial

Last Name

**PATENT**

**REEL: 054882 FRAME: 0217**

**ASSIGNMENT**

Whereas, I, **Brian Cronquist** (hereinafter referred to as Assignor(s)), residing in **Klamath Falls, Oregon**; have made a certain invention, and executed United States Patent Application entitled:

**A 3D SEMICONDUCTOR DEVICE AND STRUCTURE WITH MEMORY**

as described in U.S. Patent Application Serial No. 17/tbd and filed on about January 11, 2021;  
and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601-9300 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

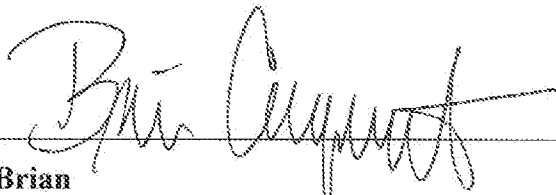
Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

**INVENTOR:**

DATE on 10 Jan 2021

  
\_\_\_\_\_  
(Brian Cronquist)  
First Name Middle Initial Last Name